	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	828	(stress or flex$4 or strain or bend$4 or bent or pressure) near4 releas$4 same slit$3	USPAT	2004/09/18 18:33
2	BRS	L2	1055	stress near4 slit$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:33
3	BRS	L6	59622	TFT or "thin film transistor"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:35
4	BRS	L7	52918	(flex$6 near2 (substrate$3 or wafer$3 or board$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:36
5	BRS	L10	335035	slit or slits	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:36

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L11	140546	(reduc$6 or less$6 or avoid$4) near4 (warp$6 or bent or bend$4 or stress)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:36
7	BRS	L12	1091	(slit or slits) same ((reduc$6 or less$6 or avoid$4) near4 (warp$6 or bent or bend$4 or stress))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:36
8	BRS	L3	45	(stress near2 releas$6) near4 slit$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:36
9	BRS	L4	17	(stress near4 slit$4) and (tape near2 carrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:36
10	BRS	L5	1307	(stress or flex$4 or strain or bend$4 or bent or pressure) near4 releas$4 same slit$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:37

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L8	28	((stress or flex$4 or strain or bend$4 or bent or pressure) near4 releas$4 same slit$3) and ((flex$6 near2 (substrate$3 or wafer$3 or board$3)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:37
12	BRS	L9	6	"stress releasing slit" or (stress-releasing adj slit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:37
13	BRS	L13	20	((slit or slits) near8 ((reduc$6 or less$6 or avoid$4) near4 (warp$6 or bent or bend$4 or stress))) and (LCD or "liquid crystal")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:37
14	BRS	L14	392	(slit or slits) near8 ((reduc$6 or less$6 or avoid$4) near4 (warp$6 or bent or bend$4 or stress))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:37
15	BRS	L15	180	((slit or slits) near8 ((reduc$6 or less$6 or avoid$4) near4 (warp$6 or bent or bend$4 or stress))) not (((slit or slits) near8 ((reduc$6 or less$6 or avoid$4) near4 (warp$6 or bent or bend$4 or stress))) and (LCD or "liquid crystal"))	USPAT	2004/09/18 18:37

	Type	L #	Hits	Search Text	DBs	Time Stamp
16	BRS	L16	372	((slit or slits) near8 ((reduc$6 or less$6 or avoid$4) near4 (warp$6 or bent or bend$4 or stress))) not (((slit or slits) near8 ((reduc$6 or less$6 or avoid$4) near4 (warp$6 or bent or bend$4 or stress))) and (LCD or "liquid crystal"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:37
17	BRS	L17	13	slit near2 releasing near2 stress	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:56
18	BRS	L18	205332	tanaka.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:56
19	BRS	L19	3340	18 and slit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 18:56
20	BRS	L20	13	19 and "flexible substrate"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 19:03

	Type	L #	Hits	Search Text	DBs	Time Stamp
21	IS&R	L22	690	(257/669).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 19:04
22	BRS	L26	64	23 and slit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 19:17
23	BRS	L27	36	26 and stress	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 19:06
24	BRS	L28	18	25 and slit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 19:17
25	IS&R	L29	1142	(257/668).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 19:30

	Type	L #	Hits	Search Text	DBs	Time Stamp
26	IS&R	L30	897	(257/E23.065).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 20:09
27	IS&R	L31	315	(257/E23.177).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/18 20:40